

Solder Paste No-Clean SAC305 in 5cc Syringe 15g T3 Mesh

Product Highlights

- Printing speeds up to 100mm/sec
- Long stencil life
- Wide process window
- Clear residue
- Low voiding
- Excellent wetting compatibility on most board finishes
- Dispense grade
- Compatible with enclosed print heads
- Passes BONO test @1.56%
- RoHS II and REACH compliant

Specifications

Alloy:	Sn96.5/Ag3.0/Cu0.5
Mesh Size:	T3
Micron (µm) Range:	25-45
Flux Type:	Synthetic No-Clean
Flux Classification:	REL0
Metal Load:	87% Metal by Weight
Melting Point:	217-220°C (423-428°F)
Packaging:	5cc/15g Syringe
Shelf Life:	Refrigerated >6 months, Unrefrigerated >2 months

Printer Operation

- Print Speed: 25-100mm/sec
- Squeegee Pressure: 70-250g/cm of blade
- Under Stencil Wipe: Once every 10-25 prints, or as necessary

Stencil Life

- >8 hours @ 20-50% RH 22-28°C (72-82°F)
- >4 hours @ 50-70% RH 22-28°C (72-82°F)

Stencil Cleaning

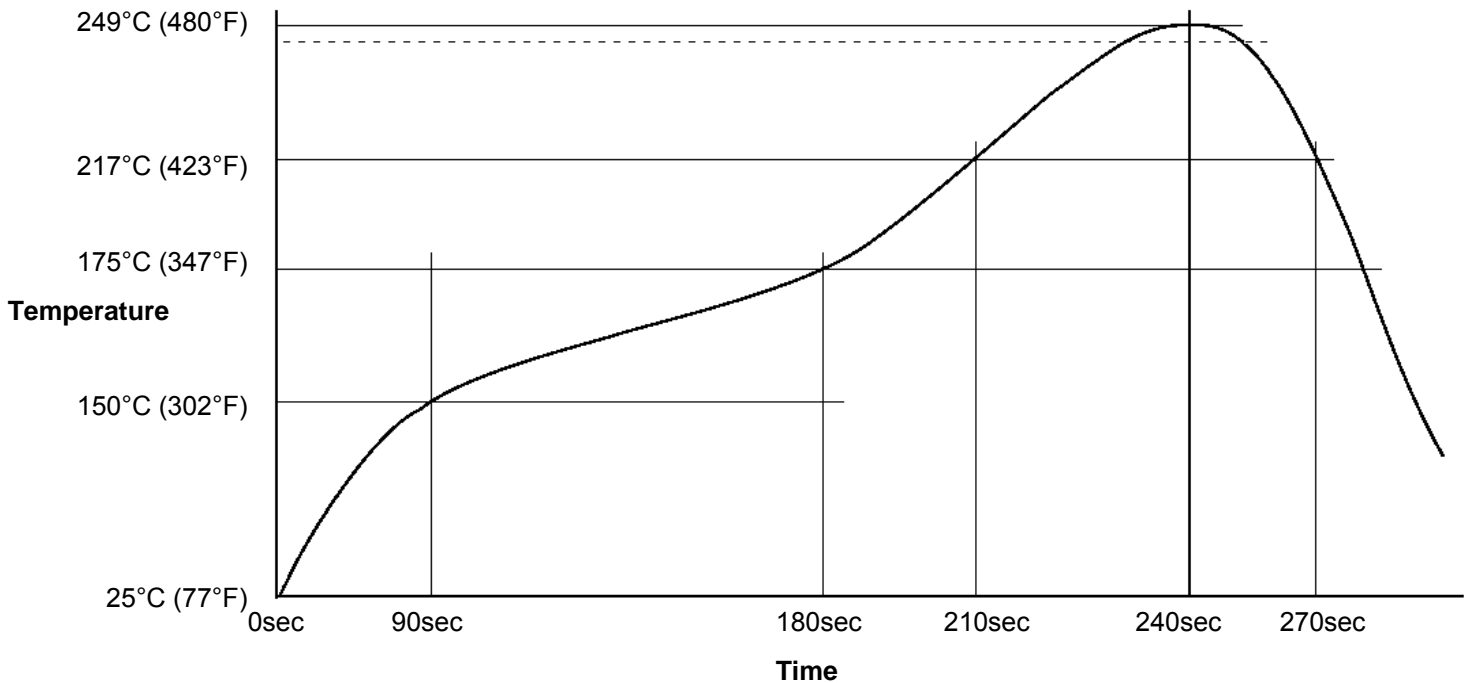
Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using isopropyl alcohol (IPA).

Storage and Handling

Refrigerate at 3-8°C (37-46°F). Do not freeze. Allow 4 hours for solder paste to reach an operating temperature of 20-25°C (68-77°F) before use.

Recommended Profile

Reflow profile for Sn96.5/Ag3.0/Cu0.5 solder assembly, designed as a starting point for process optimization.



Test Results

Test J-STD-004 or other requirements as stated	Test Requirement	Result
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.5%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (No-clean)
Surface Insulation Resistance 85°C, 85% RH @ 168 Hours	IPC-TM-650: 2.6.3.7	L: ≥100MΩ (No-clean)
Tack Value	IPC-TM-650: 2.4.44	64g
Viscosity – Malcom @ 10 RPM/25°C (x10 ³ mPa/s)	IPC-TM-650: 2.4.34.4	Print: 155-215, Dispense: 125-170
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials

Conforms to the following Industry Standards:

J-STD-004B, Amendment 1 (Solder Fluxes):	Yes
J-STD-005A (Solder Pastes):	Yes
J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):	Yes
RoHS 2 Directive 2011/65/EU:	Yes